

Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

SPECIFICATIONS:

ELECTRICAL:

RATED CURRENT: 5A RATED VOLTAGE: 300

300VDC 500VAC (rms) FOR 1 MIN

WITHSTANDING VOLTAGE: 500VAC (rms) FOR 1 M INSULATION RESISTANCE: > 1,000 mΩ at 500VDC CONTACT RESISTANCE: 13mOhms MAX DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN

OPERATING TEMPERATURE: -55°C TO +105°C

MATERIALS:

SHELL: BRACKET: INSULATOR: NICKEL PLATED STEEL NICKEL PLATED STEEL NYLON 6T, UL 94V-0, BLACK

PROCESS TEMP: 260°C

INSULATOR: CONTACT:

PATONE #322C, COLOR=Pc99 TIN PLATED PHOSPHOR BRONZE

GOLD FLASH MATING AREA
TIN PLATED SOLDER AREA

RoHS COMPLIANT

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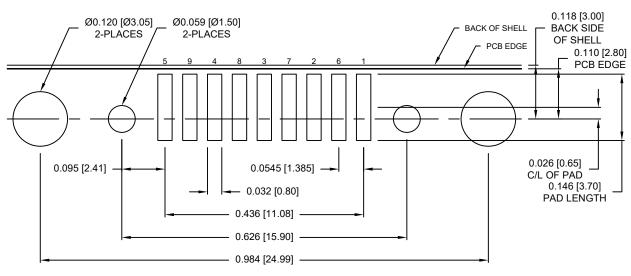
DRAWN: C. SMITH DATE: 04/14/2009

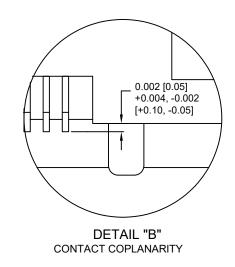
UNITS = inch [mm]

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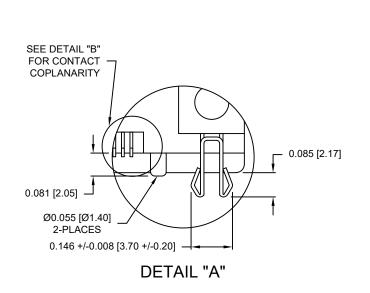
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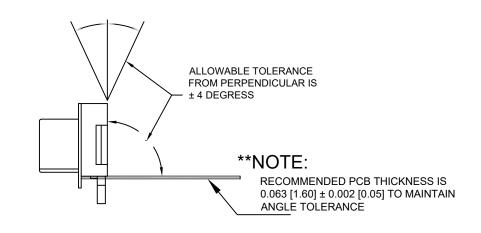




RECOMMENDED PCB LAYOUT

CONTACT ARRANGEMENT 5 9 4 8 3 7 2 6 1





ROHS COMPLIANT

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